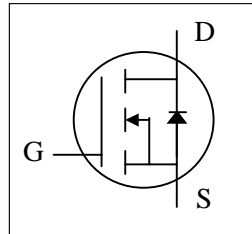


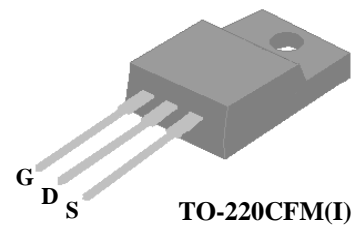
- ▼ Simple Drive Requirement
- ▼ Low On-resistance
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	80V
$R_{DS(ON)}$	8m Ω
I_D	46A

Description

XP8N8R0 series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.



The TO-220CFM package is widely preferred for all commercial-industrial through hole applications. The mold compound provides a high isolation voltage capability and low thermal resistance between the tab and the external heat-sink.

Absolute Maximum Ratings @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	+20	V
$I_D@T_C=25^\circ\text{C}$	Drain Current, V_{GS} @ 10V	46	A
$I_D@T_C=100^\circ\text{C}$	Drain Current, V_{GS} @ 10V	29	A
I_{DM}	Pulsed Drain Current ¹	200	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	31.2	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	1.92	W
E_{AS}	Single Pulse Avalanche Energy ³	45	mJ
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	4	$^\circ\text{C}/\text{W}$
Rthj-a	Maximum Thermal Resistance, Junction-ambient	65	$^\circ\text{C}/\text{W}$

Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	80	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=30A$	-	-	8	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	5	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=30A$	-	46	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=64V, V_{GS}=0V$	-	-	25	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	+100	nA
Q_g	Total Gate Charge	$I_D=30A$	-	42	67.2	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=40V$	-	13	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	11.5	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=40V$	-	15	-	ns
t_r	Rise Time	$I_D=30A$	-	58	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=6\Omega$	-	28	-	ns
t_f	Fall Time	$V_{GS}=10V$	-	63	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	2450	3920	pF
C_{oss}	Output Capacitance	$V_{DS}=40V$	-	930	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	35	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	1	2	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=30A, V_{GS}=0V$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_S=30A, V_{GS}=0V,$	-	37	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100A/\mu s$	-	28	-	nC

Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Starting $T_j=25^{\circ}\text{C}$, $V_{DD}=40V$, $L=0.1\text{mH}$, $R_G=25\Omega$

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

XSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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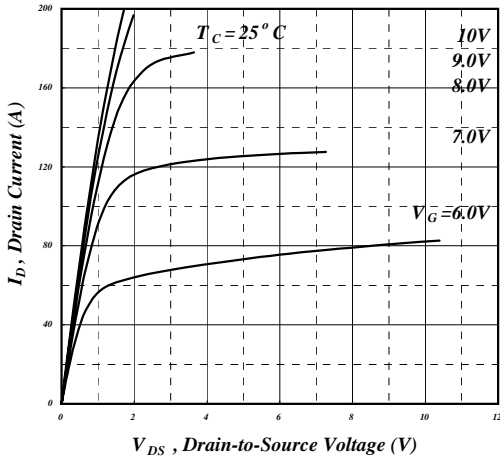


Fig 1. Typical Output Characteristics

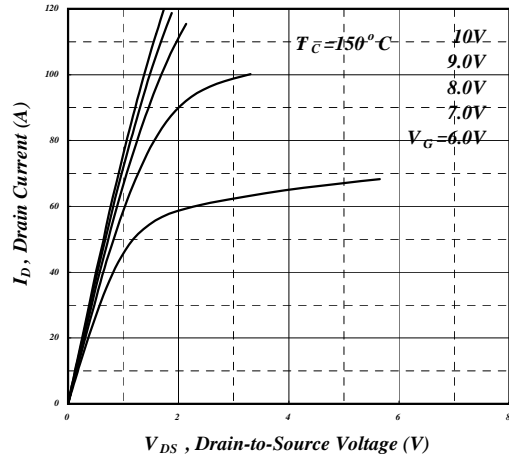


Fig 2. Typical Output Characteristics

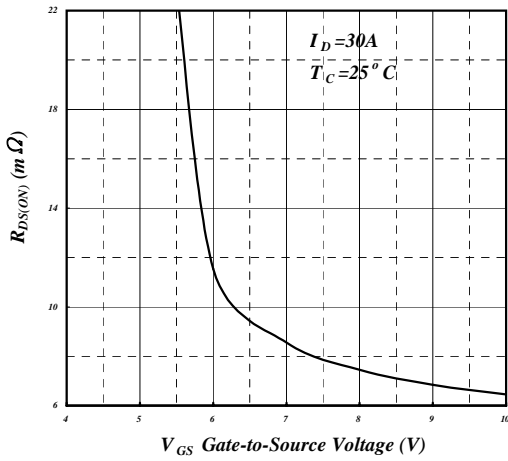


Fig 3. On-Resistance v.s. Gate Voltage

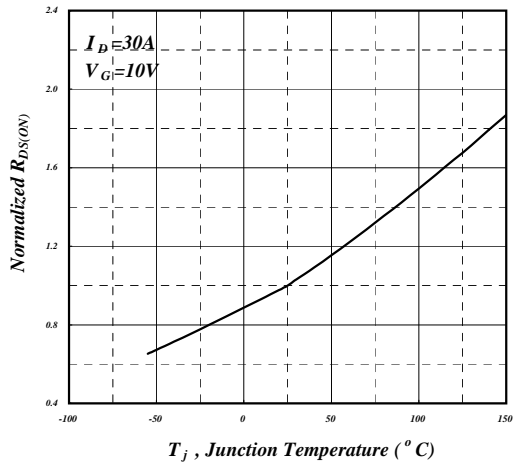


Fig 4. Normalized On-Resistance v.s. Junction Temperature

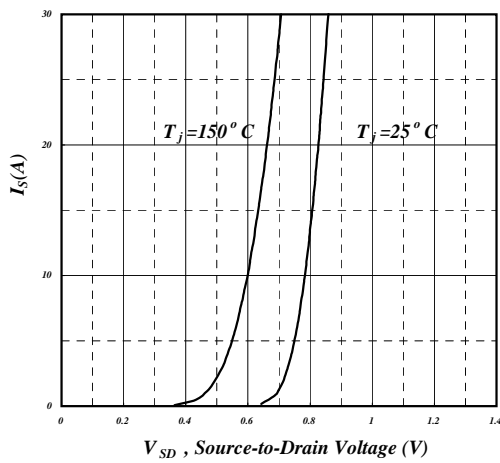


Fig 5. Forward Characteristic of Reverse Diode

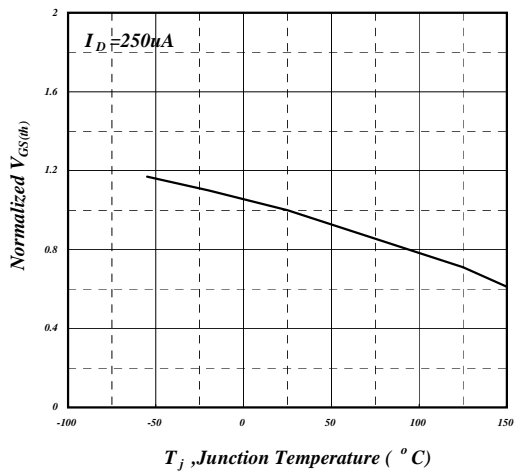


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

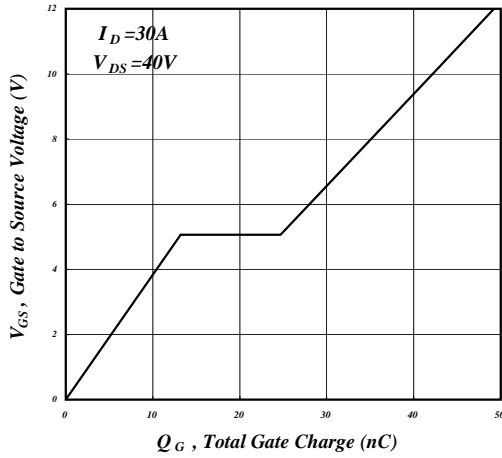


Fig 7. Gate Charge Characteristics

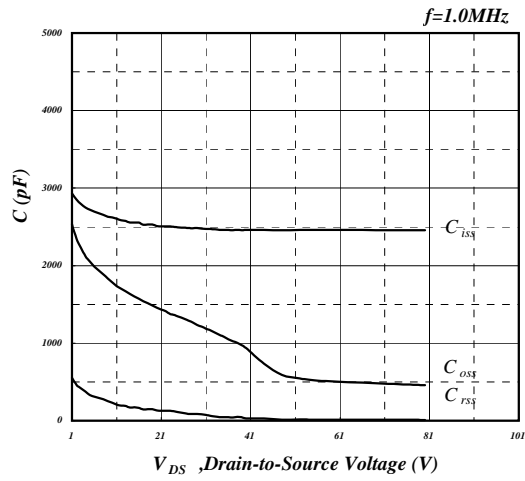


Fig 8. Typical Capacitance Characteristics

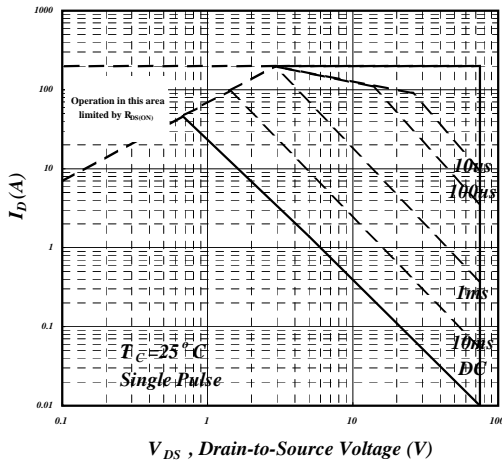


Fig 9. Maximum Safe Operating Area

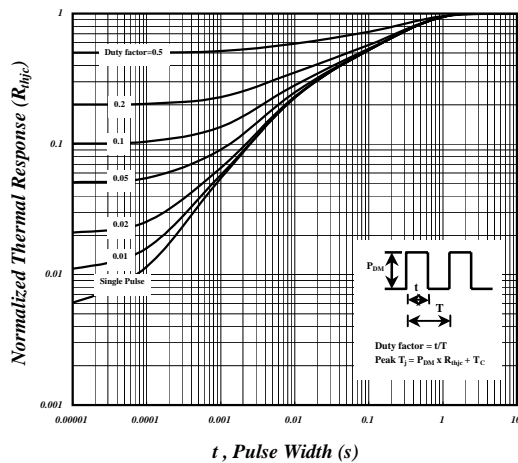


Fig 10. Effective Transient Thermal Impedance

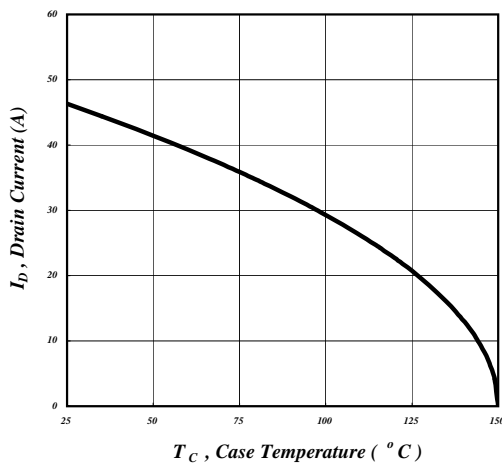


Fig 11. Drain Current v.s. Case Temperature

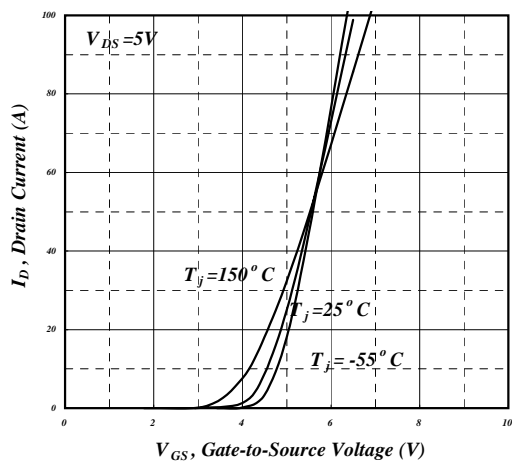


Fig 12. Transfer Characteristics

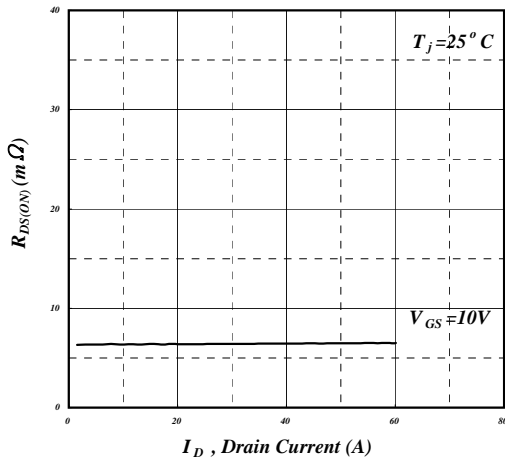


Fig 13. Typ. Drain-Source on State Resistance

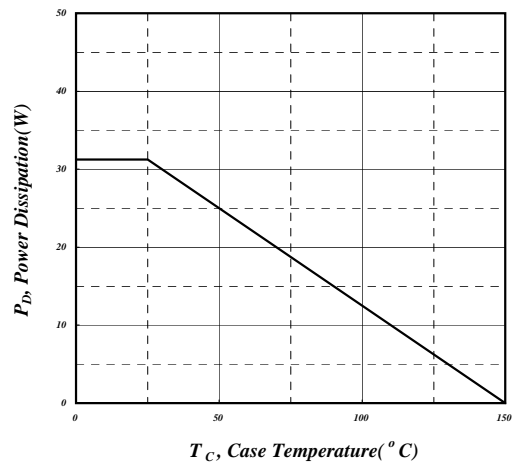
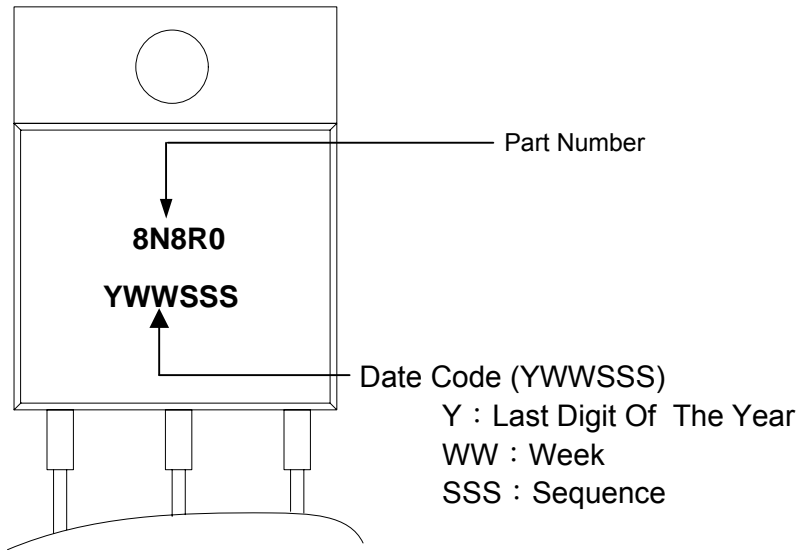
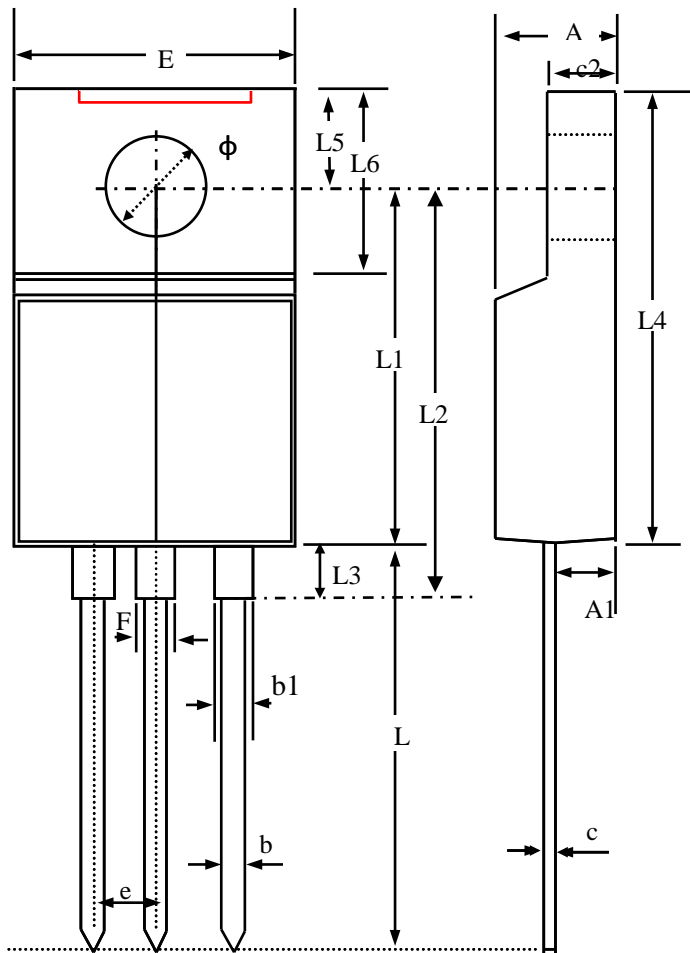


Fig 14. Total Power Dissipation

MARKING INFORMATION



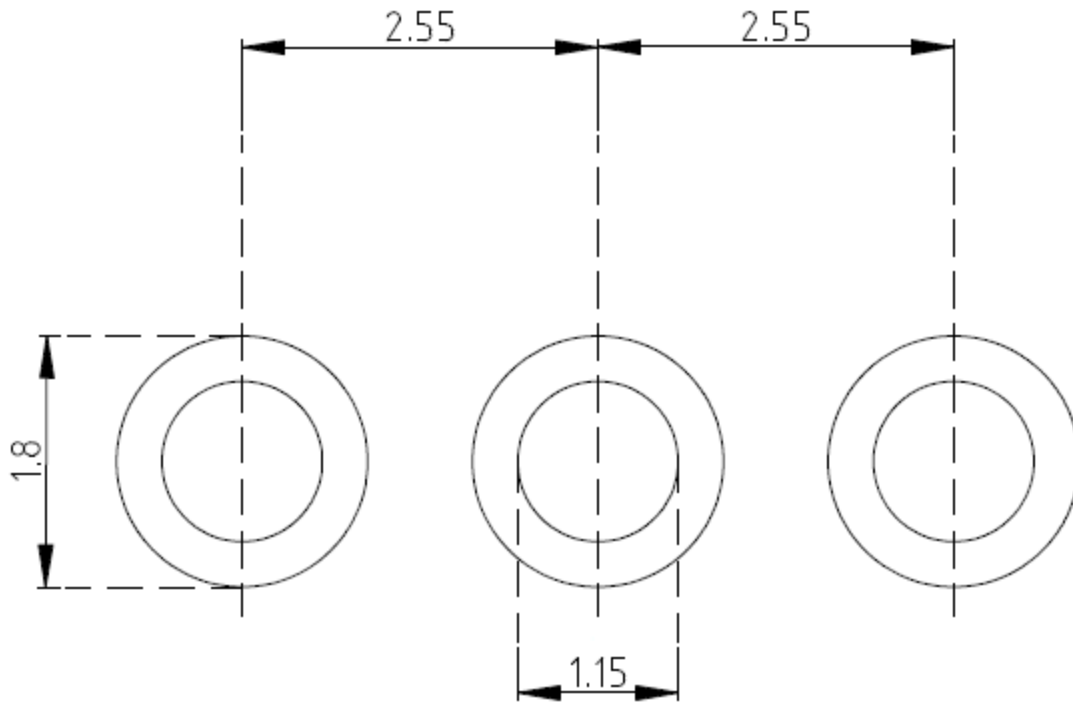
Package Outline : TO-220CFM



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.40	4.65	4.90
A1	2.50	2.68	2.86
b	0.70	0.84	0.98
b1	1.10	1.30	1.50
c	0.45	0.54	0.63
c2	2.34	2.54	2.74
E	10.00	10.20	10.40
L	12.78	13.22	13.65
L1	12.45	12.70	12.95
L2	15.10	15.80	16.50
L3	2.83	3.22	3.60
L4	15.67	16.04	16.40
L5	3.20	3.30	3.40
L6	6.50	6.73	6.95
φ	3.00	3.14	3.28
e	2.40	2.55	2.70
F	1.15	1.33	1.50

- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.

TO-220CFM FOOTPRINT :



UNIT: mm